

Claim Amendments:

This listing of claims will replace all prior versions, and listings, of claims in the application:

1. (Currently Amended) A wafer boat for supporting silicon wafers, the wafer boat comprising:
a ceramic body having at least one wafer support structure sized to support a silicon wafer thereon, the ceramic body comprising silicon carbide impregnated with silicon;
a ceramic coating disposed on a surface of the wafer support structure, the ceramic coating having an impurity migration preventing thickness that is substantially greater than or equal to 30 microns and a wafer contact surface, the wafer contact surface having a post coating surface finish;
wherein the post coating surface finish of the wafer contact surface substantially prevents frictional slip in the silicon wafers and is less than or substantially equal to 1.0 micron.
2. (Original) The wafer boat of Claim 1 wherein the wafer structure comprises at least one wafer slot sized to receive a silicon wafer therein.
3. (Original) The wafer boat of Claim 1 wherein the post coating surface finish of the wafer contact surface substantially prevents slip in silicon wafers of 300mm diameter or greater.
4. (Original) The wafer boat of Claim 1 wherein the post coating surface finish of the wafer contact surface substantially prevents slip in silicon wafers during the thermal operations reaching temperatures of 720 degrees centigrade or greater.
5. (Canceled)
6. (Original) The wafer boat of Claim 1 wherein the ceramic coating comprises a SiC.

7. (Canceled)

8. (Canceled)

9. (Previously Amended) The wafer boat of Claim 1 wherein the ceramic coating has an impurity level of substantially 1 ppm or less.

10. (Canceled)

11. (Original) The wafer boat of Claim 1, wherein the wafer boat is a vertical wafer boat.

12. (Original) The wafer boat of Claim 2 comprising:

a generally horizontal base;

a support rod extending generally vertically from the base and having at least a pair of arms extending generally parallel relative to the base, the pair of arms defining the at least one wafer slot.

13. (Original) the wafer boat of Claim 12 wherein the support rod comprises a plurality of arms defining a plurality of slots each sized to receive a silicon wafer, each slot having the ceramic coating disposed thereon to define a plurality of wafer contact surfaces, each wafer contact surface having the post coating surface finish.

14. (Original) The wafer boat of Claim 12 wherein the support rod comprises a plurality of support rods.

15. (Original) The wafer boat of Claim 12 comprising a top plate attached to the upper distal end of the support rod.

16. (Original) The wafer boat of Claim 12 wherein the base comprises a stress relief slot and a location notch.

17. (Withdrawn) A method of making a wafer boat for supporting silicon wafers, the method comprising:

providing a ceramic wafer boat body having at least one wafer support structure sized to support a silicon wafer thereon;
coating a surface of the wafer support structure with a protective ceramic coating; and
finishing the protective ceramic coating to define a wafer contact surface, the protective ceramic coating having an impurity migration preventing thickness and the wafer contact surface having a post coating surface finish, wherein the post coating surface finish substantially prevents slip in the silicon wafers.

18. (Withdrawn) The method of Claim 17 wherein coating comprises a chemical vapor deposition (CVD) process.

19. (Withdrawn) The method of Claim 17 wherein finishing comprises one of a machining operation and a laser cutting operation.

20. (Withdrawn) The method of Claim 17 wherein providing comprises providing one of a quartz body, a SiC body and a recrystallized SiC body.

21. (Withdrawn) The method of Claim 17 wherein coating comprises coating with SiC.

22. (Withdrawn) The method of Claim 17 wherein the finishing comprises finishing the ceramic coating to an impurity migration preventing thickness of substantially 30 microns or greater.

23. (Withdrawn) The method of Claim 17 wherein finishing comprises finishing the ceramic coating to an impurity migration preventing thickness of 60 microns nominal.

24. (Withdrawn) The method of Claim 17 wherein coating comprises coating with a ceramic coating having a purity level of less than or substantially equal to 1 ppm.

25. (Withdrawn) The method of Claim 17 wherein finishing comprises finishing the ceramic coating to define a wafer contact surface having a post coating surface finish of less than or substantially equal to 0.4 microns.

26. (Withdrawn) The method of Claim 17 comprising:
dimensionally undersizing the critical dimensions of the ceramic body by a predetermined amount; and
compensating for the undersized critical dimensions by the predetermined thickness of the protective coating applied.

27. (Withdrawn) The method of Claim 26 comprising:
processing SiC in molds to produce a set of green body parts, which include a plurality of support rods, a base and a top plate;
subjecting the set of body parts to a recrystallization process;
assembling the set of body parts to form the unfinished ceramic body;
impregnating the ceramic body with high purity silicon metal;
sandblasting the ceramic body;
machining of the ceramic body;
CVD coating the entire body with high purity SiC; and
post CVD finishing the ceramic body to define the wafer contact surfaces.

28. (Canceled)

29. (Previously Presented) The wafer boat of Claim 1 comprising:
a base;
a plurality of support rods extending generally upwards from the base, each support rod including at least one arm extending generally inwardly relative to the base, each arm having the post coating surface finish disposed thereon.

30. (Currently Amended) A wafer boat for supporting silicon wafers while substantially eliminating friction slip in said silicon wafers, the wafer boat comprising: a ceramic body having at least one wafer support structure sized to support a silicon wafer thereon, the ceramic body comprising silicon carbide impregnated with silicon; a ceramic coating disposed on a surface of the wafer support structure, the ceramic coating having an impurity migration preventing thickness that is substantially between 30 to 60 microns and a wafer contact surface, the wafer contact surface having a post coating surface finish; wherein the post coating surface finish is less than or substantially equal to 0.4 microns.

31. (Canceled)

32. (Previously Presented) The wafer boat of Claim 30 comprising:
a base;
a plurality of support rods extending generally upwards from the base, each support rod including at least one arm extending generally inwardly relative to the base, each arm having the post coating surface finish disposed thereon.